

# Thin flex glass (TFG) workshop

14.05.14



Ultrafast laser processing of thin film interconnections in  
microelectronic, display, and photovoltaic applications

- ❖ Housekeeping
  - ❖ Toilets
  - ❖ Evacuation
  - ❖ Smoking
  
- ❖ Meeting agenda
  - ❖ Presentations
  - ❖ Posters
  - ❖ Demonstrations
  - ❖ Round up discussion
  
- ❖ Flexible Large Area Electronics (F-LAE)
  - ❖ Large Area Electronics processes
  - ❖ S2S LAE tools & applications
  - ❖ F-LAE roadmap
  - ❖ Thin Flex Glass

# Evolution to F-LAE

## Large Area Electronics (LAE)



## Flex Large Area Electronics (F-LAE)

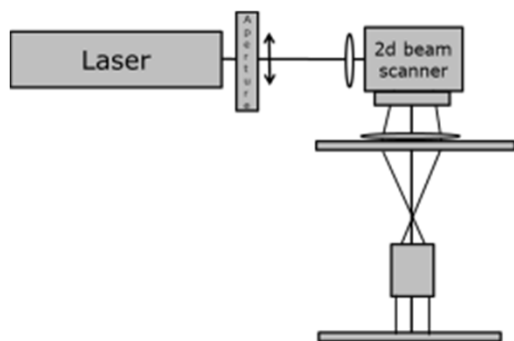
# Material additive & subtractive processes for LAE



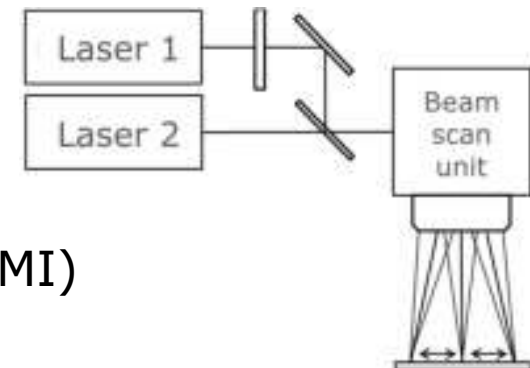
- ❖ Additive processes
  - ❖ ink jet print
  - ❖ laser cure/expose
  - ❖ spray



- ❖ Subtractive laser ablation processes



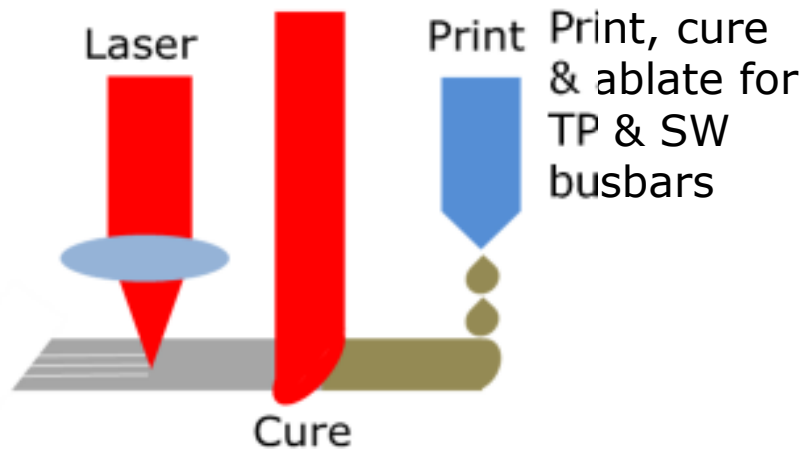
- ❖ Direct write
- ❖ Aperture image
- ❖ Scanned mask image (SMI)
- ❖ Raster scan



Our direct laser ablation processes replace conventional lithographic processes

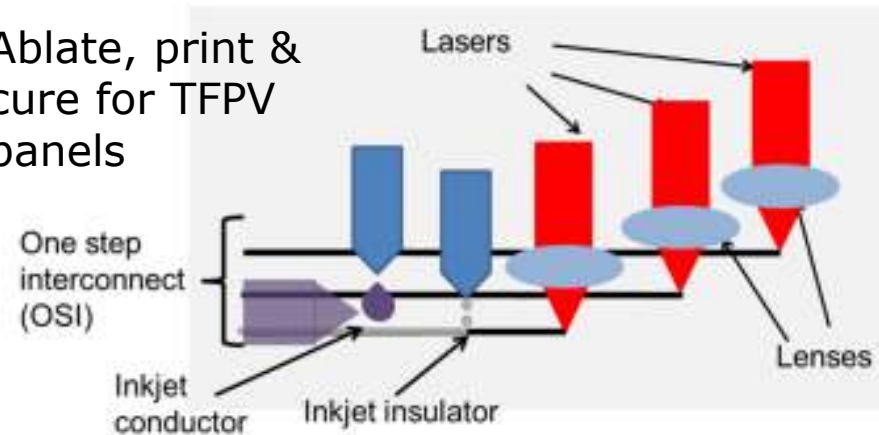
Our resolution limit is a few microns

# Hybrid additive & subtractive processes to “interconnect” LAE devices



Other hybrid processes use lasers to modify surfaces to control printing

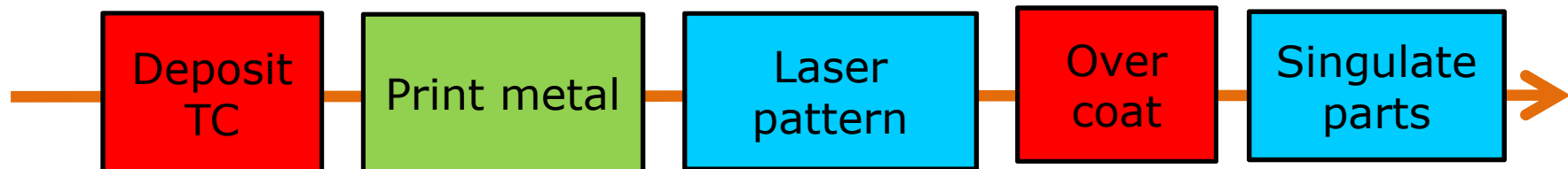
Ablate, print & cure for TFPV panels



Other hybrid TP process require laser, print & spray steps

# Our Flexible Large Area Electronics strategy

Develop a complete portfolio of R2R tools suitable for the manufacture of flexible “Large Area Electronics (F-LAE)” devices based on M-Solv additive, subtractive and hybrid processes



# F-LAE R2R tools

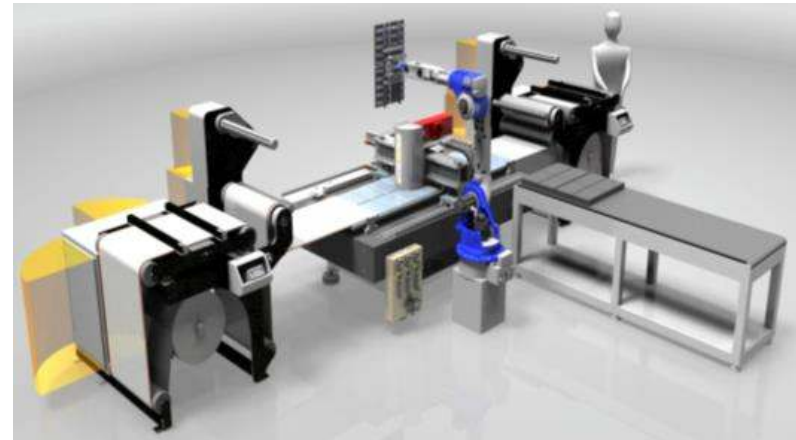
“Batch Process” R2R tools  
Web is stationary during process



MSV-6505 ITO/PET patterning tool



0.65m  
wide  
web

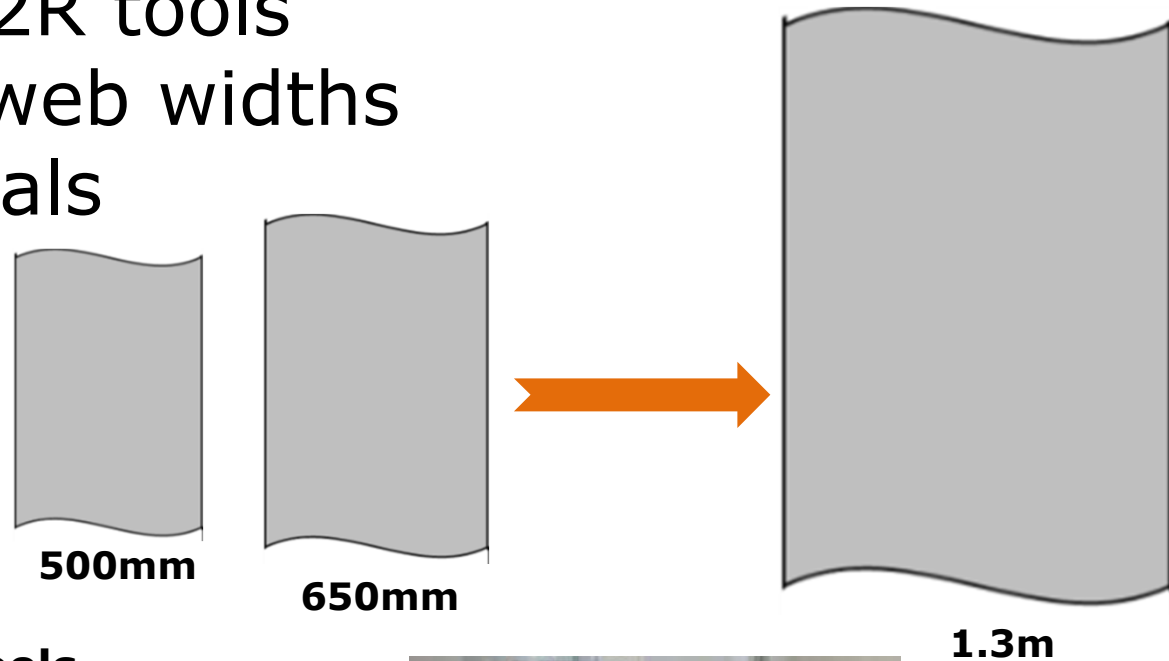


MSV-6501 ITO/PET cutting tool



# F-LAE tool roadmap

- ❖ 3 standard R2R tools
- ❖ 3 maximum web widths
- ❖ 3 web materials
  - ❖ PET
  - ❖ SS
  - ❖ TFG



## Gen 1 tools

500mm TFG & SS tools  
650mm PET tools



1.3m TFG, PET  
& SS tools

## Gen 2 tools



# Thin Flex Glass (TFG)

- ❖ Why use TFG?
- ❖ **Applications**
- ❖ Sheets or spools?
- ❖ What TC coatings
- ❖ What processes?
- ❖ Transportation & handling?

# Why use TFG?

- ❖ Barrier properties?
- ❖ Thermal properties?
- ❖ Optical properties?
- ❖ Mechanical properties?

# Accessible R2R TFG applications

- ❖ OLED lighting
- ❖ Thin Film PV
- ❖ Smart windows
- ❖ PM LCDs
- ❖ LC signage
- ❖ Thin film batteries
- ❖ Large AM displays
- ❖ Sensors
- ❖ Capacitive touch panels
- ❖ 2.5 & 3D IC interposers
- ❖ ??

The primary objective of this workshop is to get a better understanding of where TFG will be used as a device substrate and where R2R mode processing is preferred

Key applications are for 2 and 2.5D devices where the barrier properties of TFG are critical

## TFG on sheets or spools?

- ❖ High resolution device manufacturers wish to use TFG with their existing process tools
- ❖ These are all sheet (eg  $\geq G5$ ) based
- ❖ No R2R TFG high resolution tools yet exist
- ❖ Hence TFG manufacturers are delivering in sheet form on glass carriers
  - ❖ Complex bond & de-bond processes required

We focus on TFG in spooled form since it:

- ❖ Matches our processes well
- ❖ Has lowest cost of ownership

# TFG R2R pilot tool

Multi-function  
pilot R2R tool

- ❖ Print
- ❖ Cure
- ❖ Pattern
- ❖ Cut

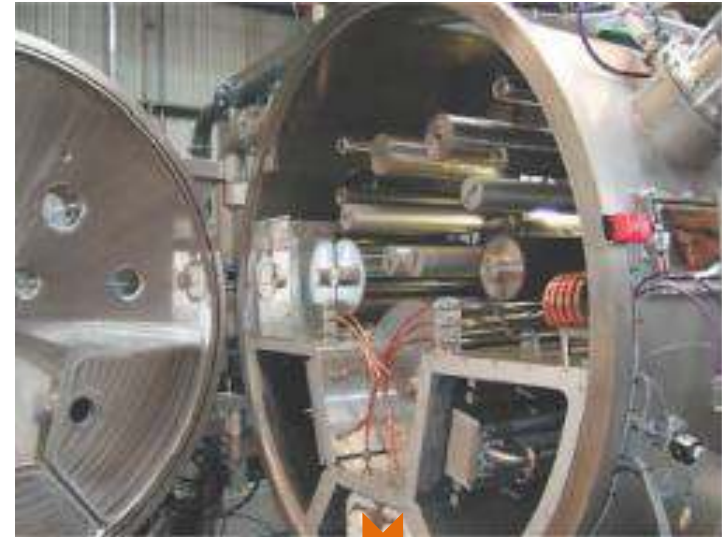
500mm  
wide TFG



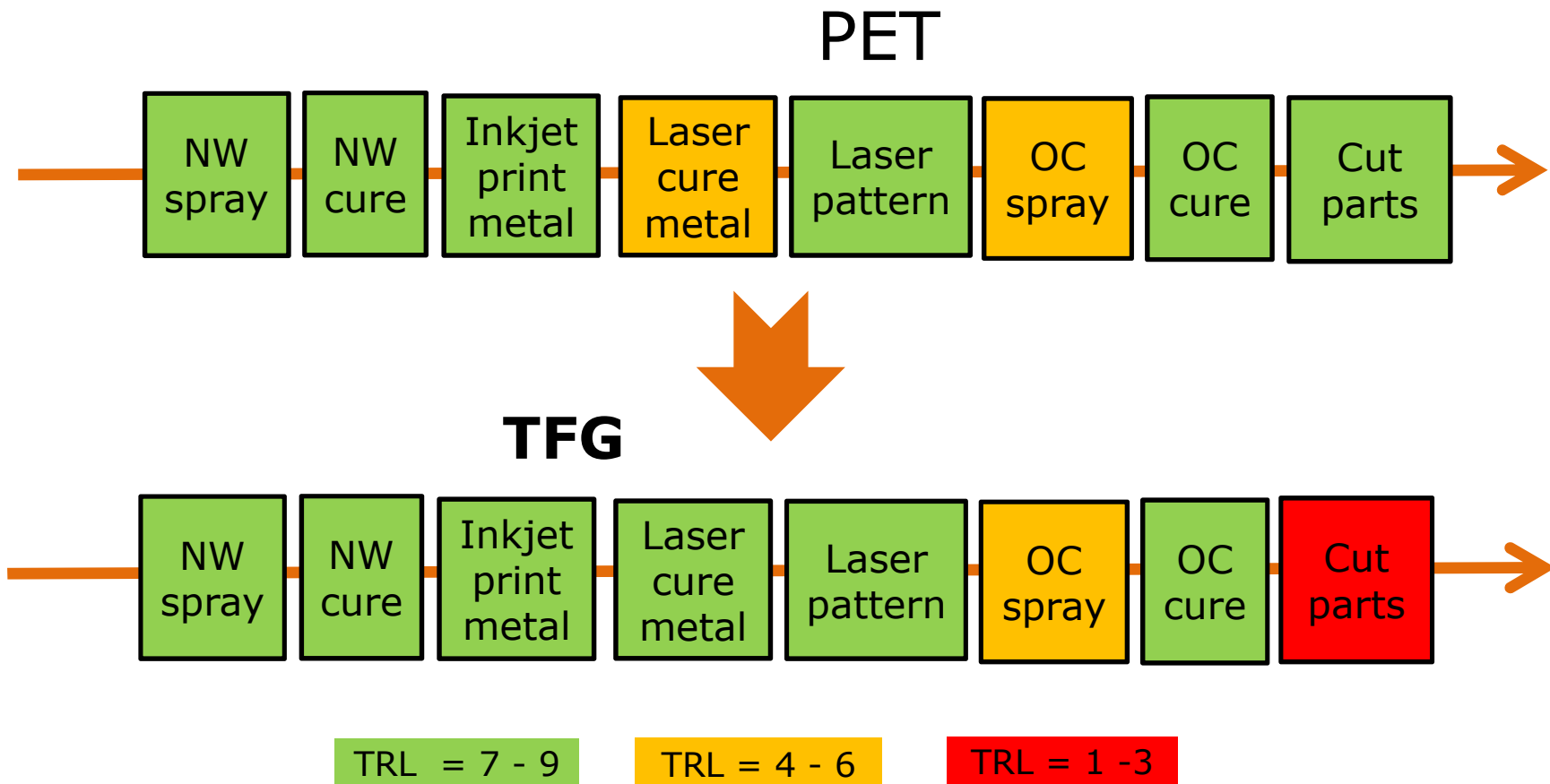
“Batch Process” R2R tool  
Web is stationary during process

# TC coatings on TFG

- ❖ Many TFG applications require a transparent conductive (TC) coating
- ❖ ITO is optimum but difficult to coat in R2R mode, is expensive and is not flexible
- ❖ We have developed a AgNW based TC
- ❖ We have fabricated advanced touch sensors on TFG with AgNW TC



# TFG R2R process status



# TFG R2R web handling status

